2.830J / 6.780J / ESD.63J Control of Manufacturing Processes (SMA 6303) Spring 2008

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Control of Manufacturing Processes

Subject 2.830/6.780 Spring 2008 Lecture #3 "Process Variation – Physical Causes and Interpreting Data"

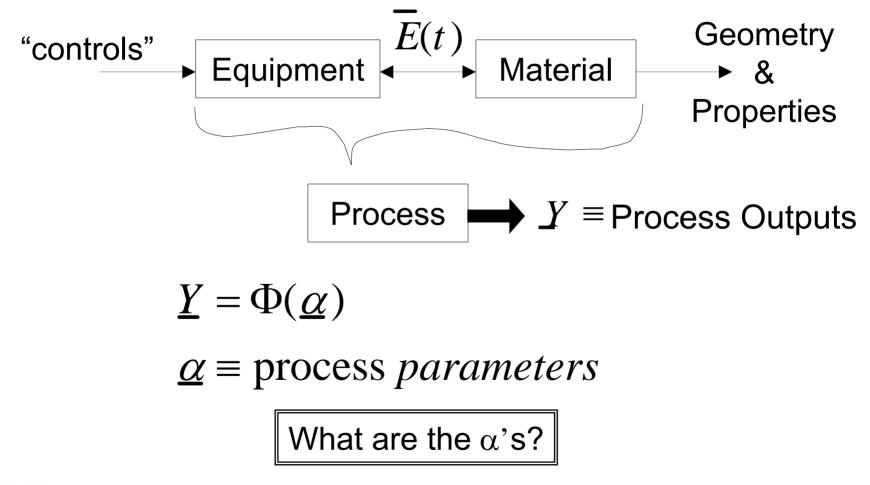
February 12, 2008

Agenda

- Process Definitions
 - Geometry Change Causality
- Taxonomy for Control
 - Classification of Change Methods
- "Mechanical" Examples
 - Turning
 - Bending
 - Molding
- Origins of Variation
 - States and Properties



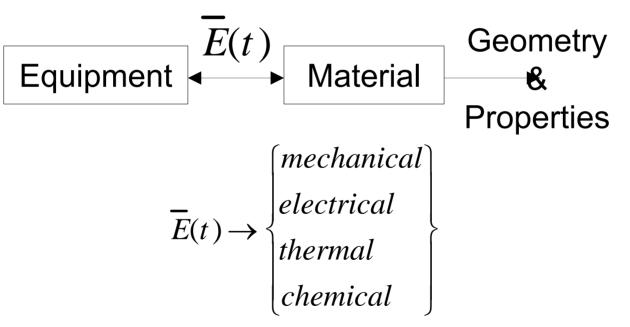
Process Model for Control





Back to the Process: What Causes the Output Change?

 A Directed Energy Exchange with the Equipment





Modes of Geometry Change?

- Removal of Material
- Plastic Deformation of Material
- Addition of Material
- Formation of Material from a Gas or Liquid
- Any others???



What Controls the Geometry Change?

Location and Intensity of Energy Exchange

• Examples:

- location of max. shear stress in turning

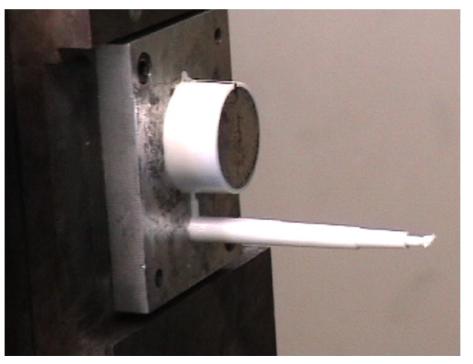




What Controls the Geometry Change?

Location and Intensity of Energy Exchange

- Examples:
 - heat transfer at the mold surface in injection molding





Control of Geometry Change?

Location and Intensity of Energy Exchange

• Examples:

– location of laser
 beam in laser cutting





Control of Geometry Change?

Location and Intensity of Energy Exchange

- reaction rate - time product on substrate surface in LPCVD

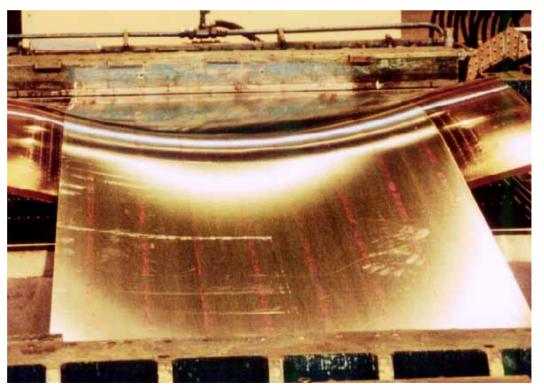




Control of Geometry Change?

Location and Intensity of Energy Exchange

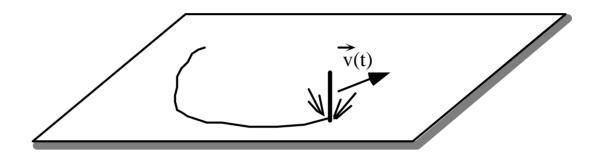
• displacement field in sheet forming :



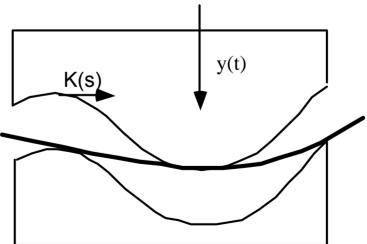


Two Extremes of Interactions

Area of E(t) << Total Area: Serial Process



Area of $E(t) \sim$ Total Area: Parallel Process





Two Extremes of Interactions

- Concentrated, "Lumped" Energy Port

 Small Area Wrt Total Part Geometry
- Distributed Energy Port
 - Area ~ Total Part Geometry



What Determines Part Geometry Change?

- For Lumped case:
 - time trajectory of the port location
 - e.g. tool paths
- For Distributed Case:
 - Shape of the energy distribution
 - patterns
 - molds
 - masks



Examples

- Serial (Lumped) Processes
 - Machining
 - Laser Cutting Beam path
 - Bending
 - Stereolithography Beam Path
 - Three D Printing Binder Path

- **Tool Path**
- - **Tool Depth**



Examples

- Parallel (Distributed) Processes
 - Draw Forming
 - Injection Molding –
 - Chemical Etching Mask Shape
 - -CMP
 - Plating

- **Die Shapes** _
 - Mold Shape
- - **Tool Shape**
 - Substrate Shape



Toward a Process Taxonomy

- Classify by Change Mode – Why?
- Classify by Intera Sensitivity, resolution arallel)
 So what?
- Classify by Energy Domain

- Who cares??

Flexibility, controllability, rate

Rate, resolution



Process Taxonomy for Control

Transformation				REM	IOVAL			
Mode	SERIAL				PARALLEL			
Energy Source	Mechanical	Thermal	Chemical	Electrical	Mechanical	Thermal	Chemical	Electrical
	Cutting	Laser Cuttin	g	WIRE EDM	Die Stamping	-	ECM	EDM
	Grinding "Flame" Cutting				CMP		Photolithogra	aphy
	Broaching	Plasma Cutti	ing				Chem Milling	7
	Polishing		-				-	
	Water Jet							

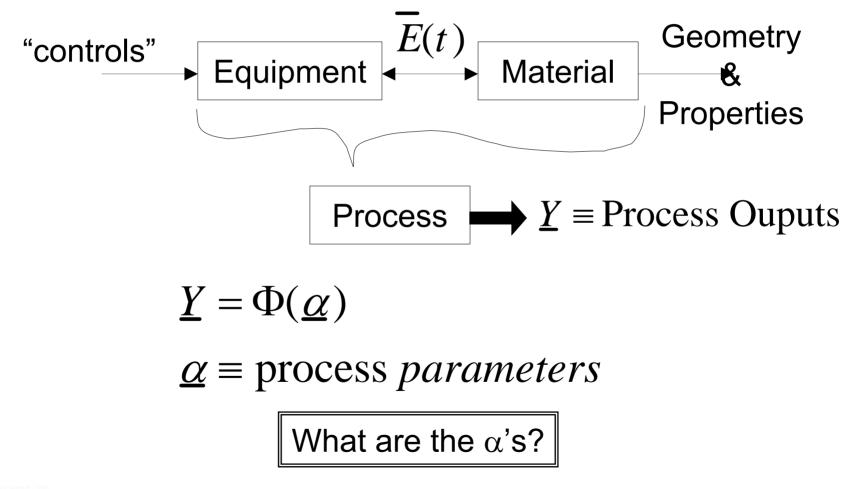
Transformation				ADDITION/	JOINING				
Mode		SE	RIAL		PARALLEL				
Energy Source	Mechanical	Thermal	Chemical	Electrical	Mechanical	Thermal	Chemical	Electrical	
	Ultrasonic	Laser		E-Beam Welding	HIP	Sintering	LPCVD		
	Welding	Sintering		Arc Welding	Inertia Bonding)	Plating		
	3D Printing			Resist. Welding	Phys. Depos.		-		

Transformation				FORMA	ΓΙΟΝ			
Mode	SERIAL			PARALLEL				
Energy Source	Mechanical	Thermal	Chemical	Electrical	Mechanical	Thermal	Chemical	Electrical
	-	Plasma Spray	Stereolithograp	hy		Casting	Diffusion	
		DBM				Molding	Bonding	

Transformation				DEFORM	ATION			
Mode	SERIAL				PARALLEL			
Energy Source	Mechanical	Thermal	Chemical	Electrical	Mechanical	Thermal	Chemical	Electrical
	Bending	Line Heating	-	•	Drawing	•		
	Forging(open)				Forging(die)			
	Rolling							



Process Model for Control





Process Parameters

- Equipment Energy "States"
- Equipment Constitutive "Properties"
- Material Energy "States"
- Material Constitutive "Properties"

$$- \mathbf{F}_{equipment} \stackrel{\overline{E}(t)}{\bullet} \text{Material} \stackrel{\overline{E}(t)}{\bullet}$$



Energy States

Energy Domain	Energy or Powe	<u>r Variables</u>
Mechanical	F, v; P, Q or	· F, d ; σ, ε
Electrical	V,1	
Thermal	T, ds/dt	(or dq/dt)
Chemical	chemical pote	ential, rate

$$\rightarrow \text{Equipment} \stackrel{\overline{E(t)}}{\longleftarrow} \text{Material} \rightarrow$$

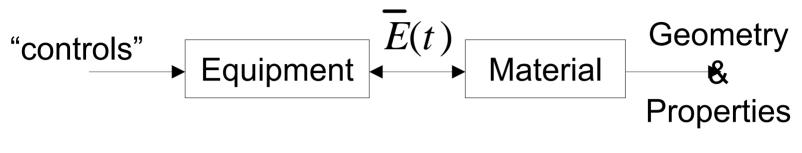


Properties

- Extensive: <u>GEOMETRY</u>
- Intensive: Constitutive Properties
 - Modulus of Elasticity, damping, mass
 - Plastic Flow Properties
 - Viscosity
 - Resistance, Inductance, Capacitance
 - Chemical Reactivity
 - Heat Transfer Coefficient



A Model for Process Variations



- Recall: $\underline{Y} = \Phi(\underline{\alpha})$
- One or more α 's "qualify" as inputs : <u>u</u>

$$\underline{Y} = \Phi(\underline{\alpha}, \underline{u}); \qquad \underline{u} = \text{vector of inputs}$$

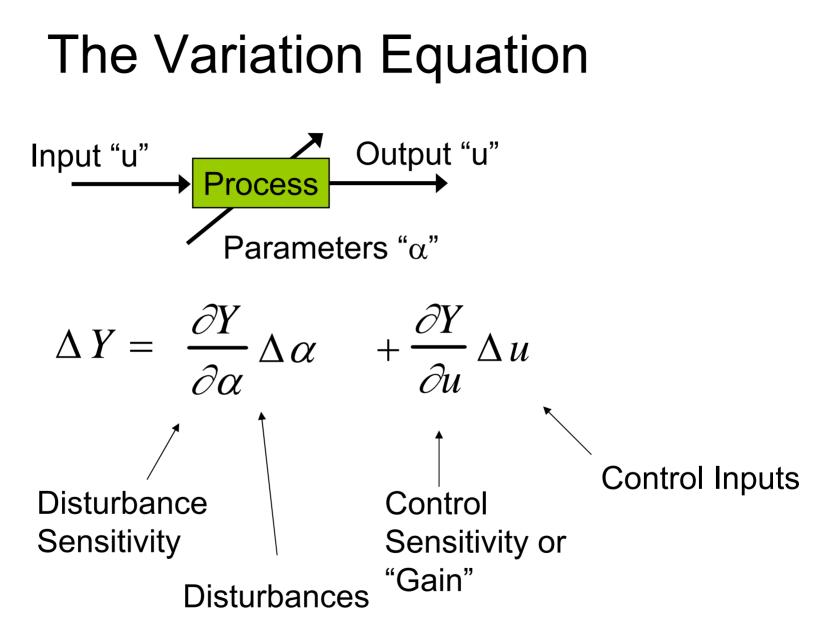
 The first order Variation ∆Y gives the "Variation Equation"



Parallels From Lecture 2

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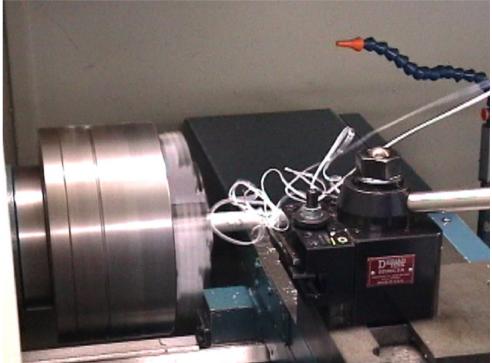




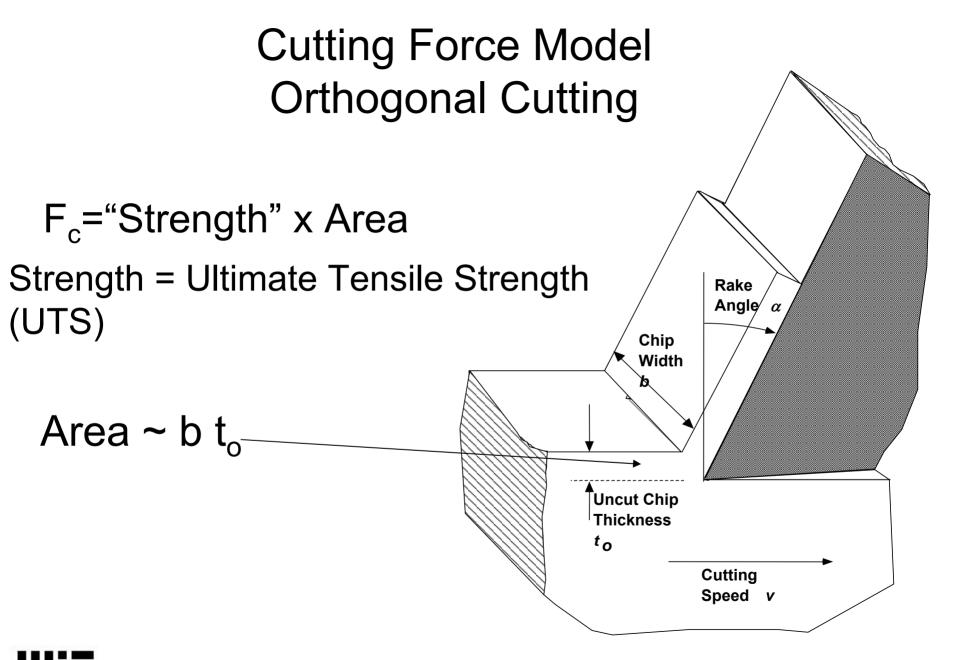


Simple Machining

- Process Type?
- Equipment States and Properties?
- Material States and Properties?

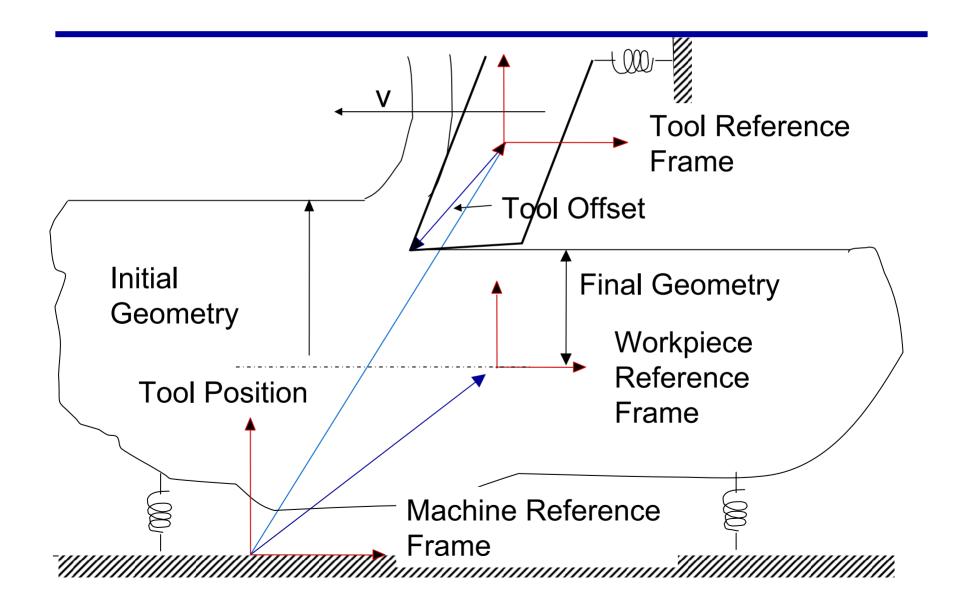




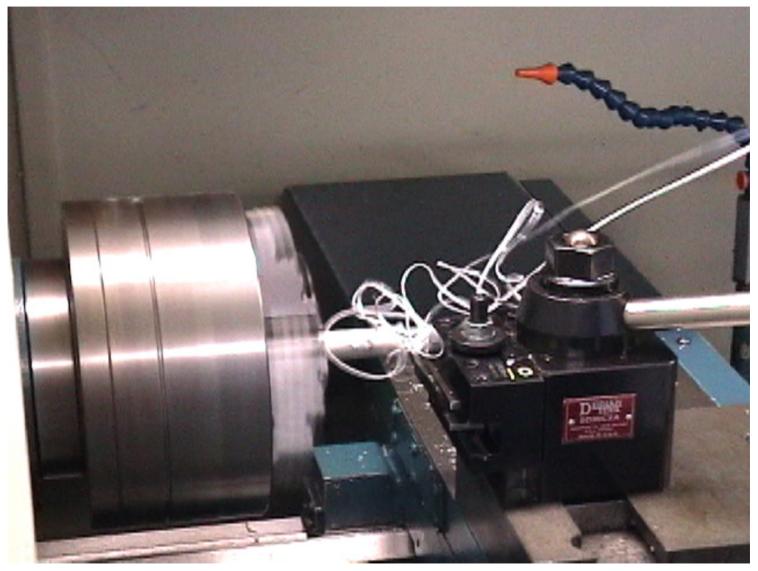




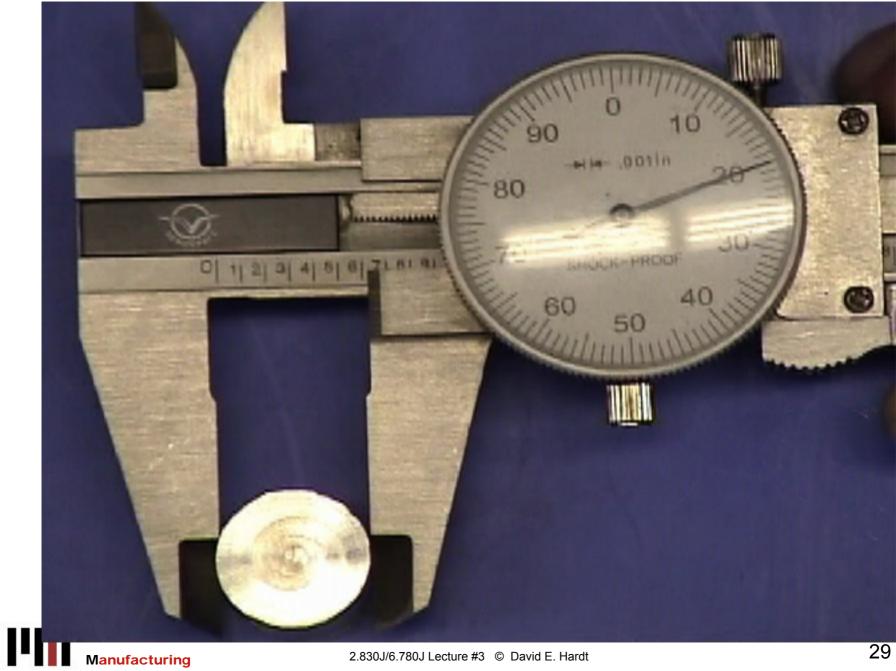
Sources of Variation?



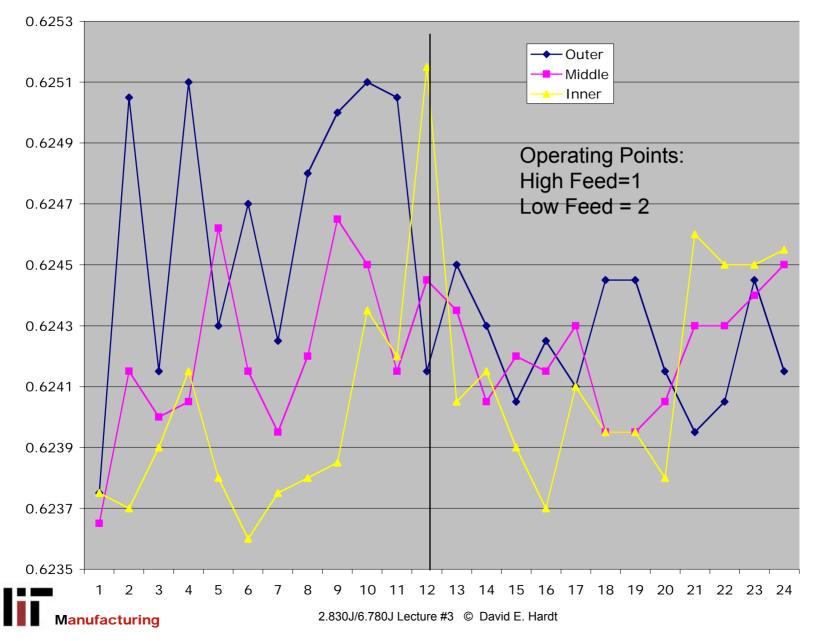
Simple Machining (Orthogonal Turning



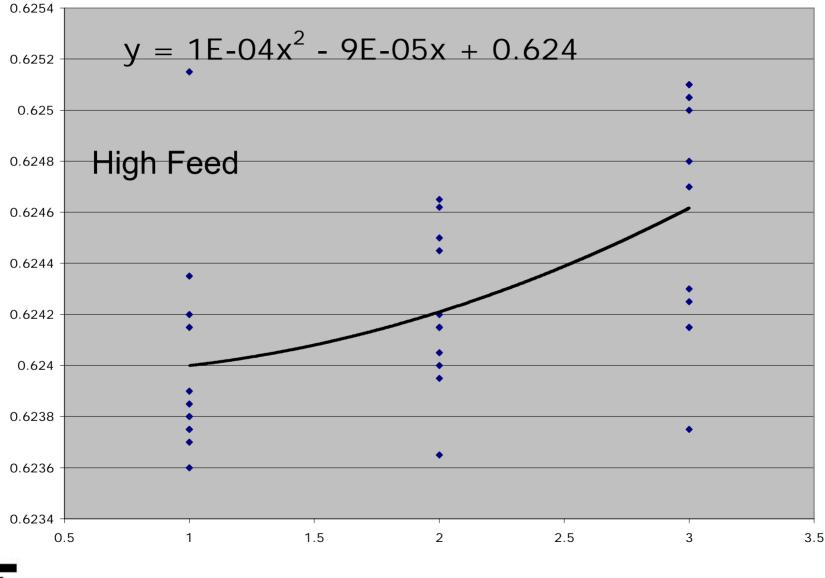




CNC Data

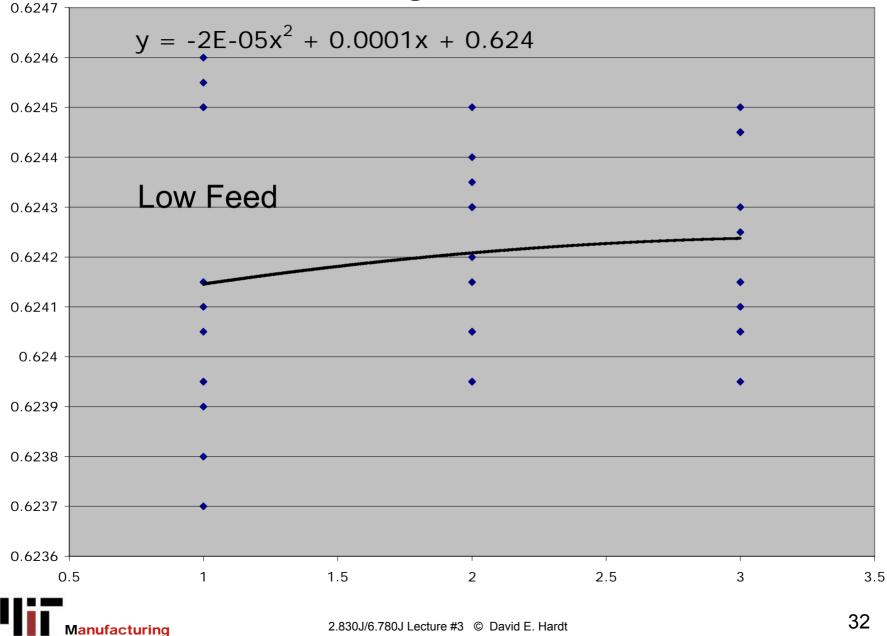


Average Values



Manufacturing

Average Values

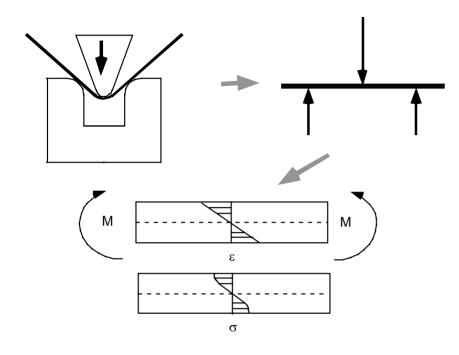


Machining: Conclusions

- Geometry Transformation is (In General) well behaved
 - Not highly sensitive to material property variations
 - New Surface Where Tool is Located
- Dominant Sources of Variation:
 - Tool Positioning errors Equipment Properties and States
- Feedback control of Positions is a good idea
 -> CNC control!



Brake Bending



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http://www.falconfab.com/MVC-016F.JPG

http://www.falconfab.com/MVC-007F.JPG

http://edevice.fujitsu.com/fj/DATASHEET/epk/fpt-100p-m20.pdf

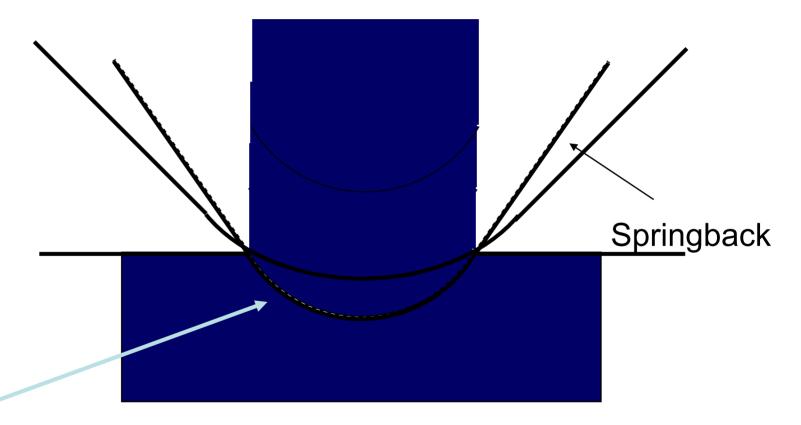


Bending

- Process Type?
- Equipment States and Properties?
- Material States and Properties?



Simple Model : Pure Moment Bending



Constant Radius Tool

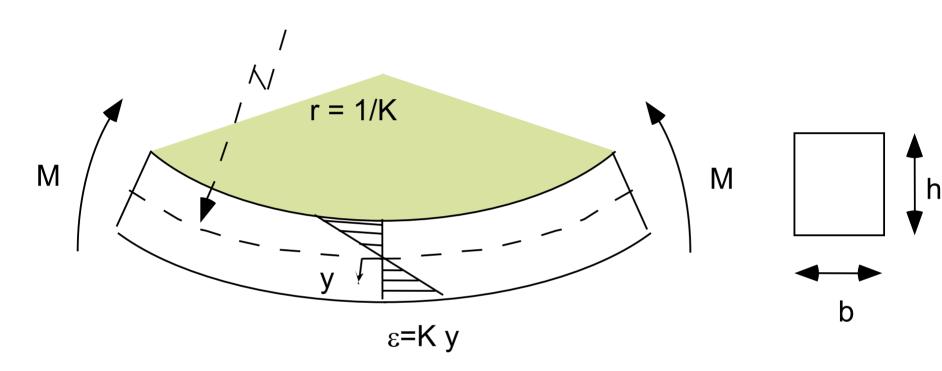


Simple Bending Mechanics: Parameter Effects

- Tool Shape (R_{tool}) determines the shape under load
- Elastic Springback determines the final shape
- What determines the springback?

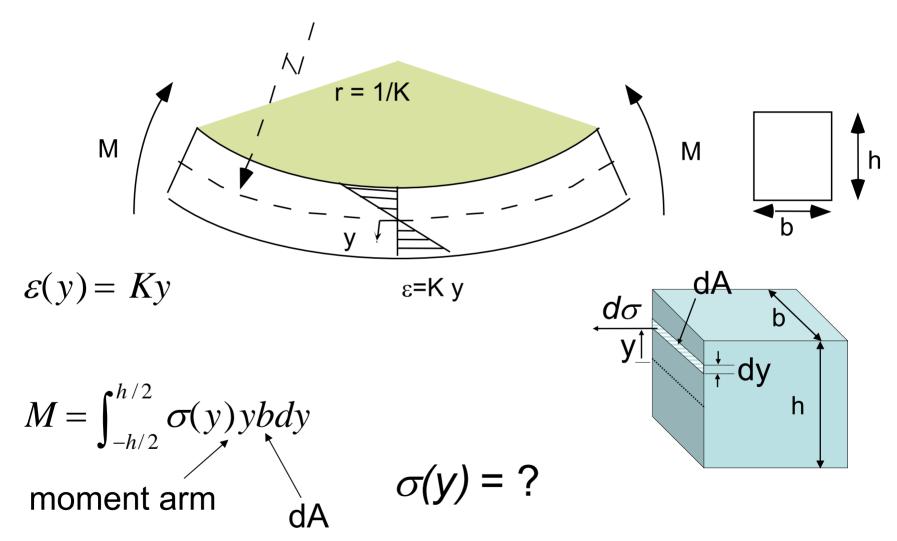


Simple Bending Model



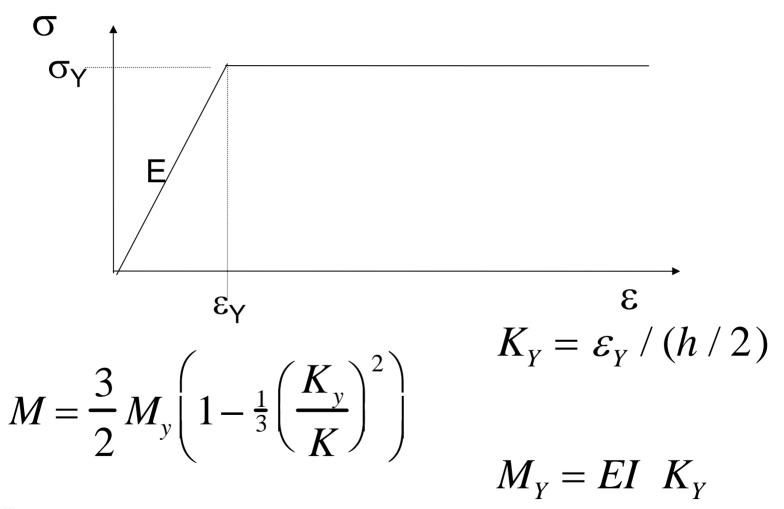
 $K = curvature of the tooling
h = thickness of the sheet
<math>\epsilon(y) = through thickness strainWhat is M(K)
(or K(M)) ?$

Simple Beam Theory



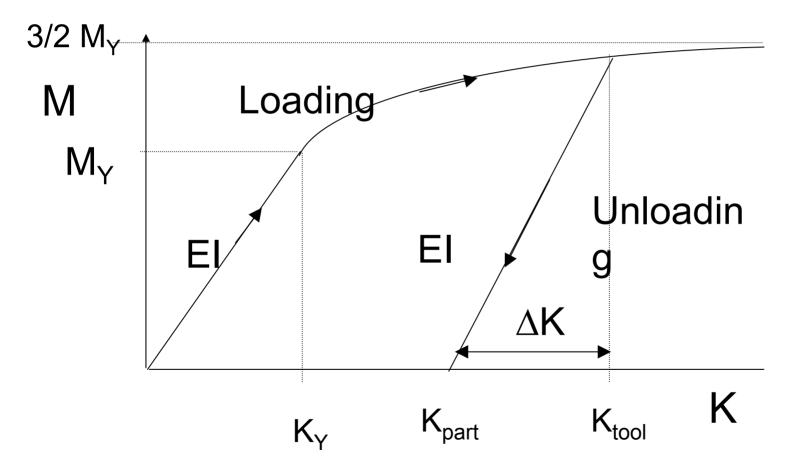


Elastic Perfectly Plastic Model





The M-K Curve





Final Shape: Springback

$$\Delta K = \frac{M_{\text{max}}}{EI} \therefore K_{part} = K_{tool} - \Delta K$$

K = shape of tool

E= material property $I = \frac{1}{12}bh^3$ cubic dependence on thickness

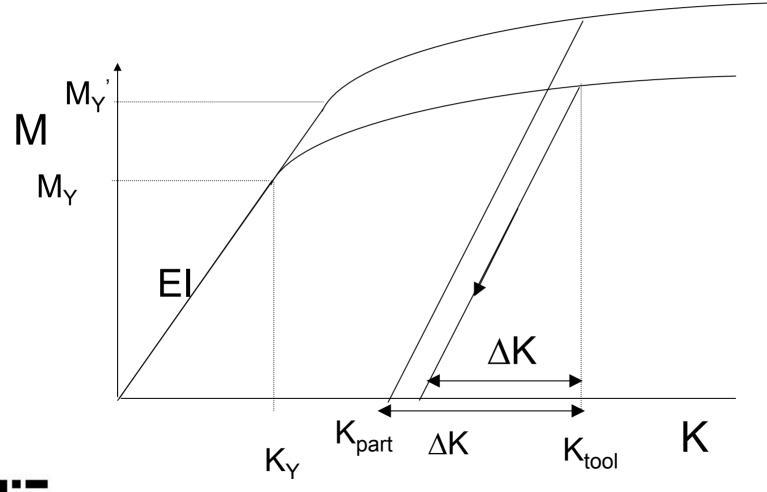
$$M_{\rm max} = ?$$

$$M_{\rm max} = \Phi ({\rm K}_{\rm Y}, EI)$$

Strong Dependence on yield properties



Effect of Material Variations: Increase in Yield Stress





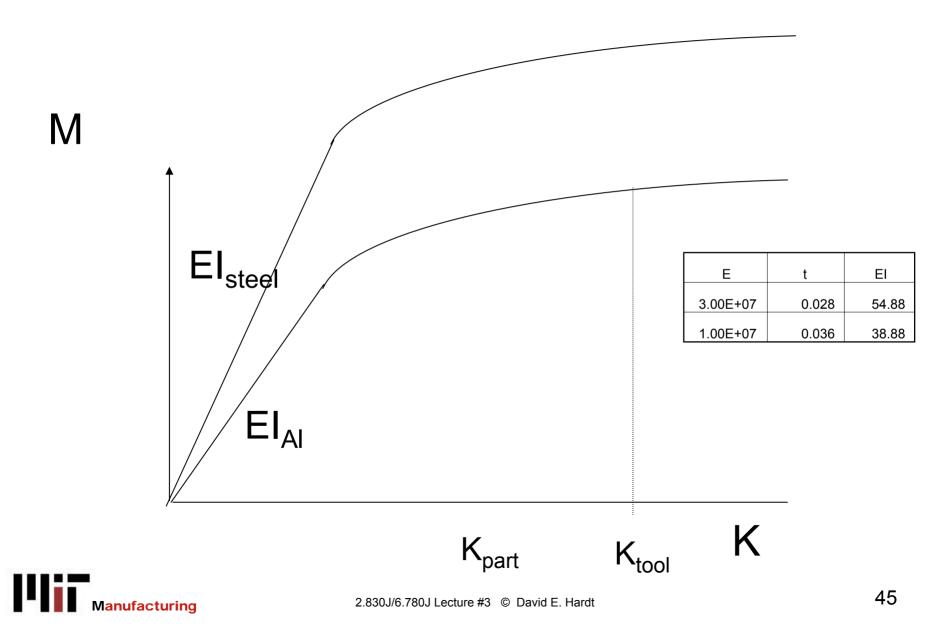
Bending Experiments



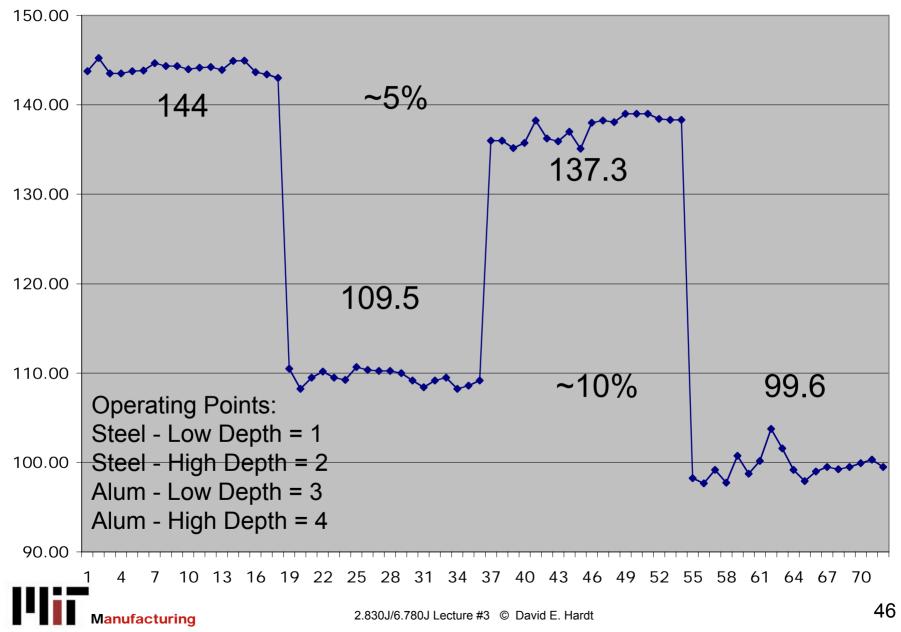
- Bend to 2 different depths
- Two different materials
 - 0.028" Steel
 - 0.032" Aluminum



Steel vs. Aluminum



Bending by Operating Point



Other Possible Variations

- Yield Stress (<u>+ 10%reported</u>)
 Chemistry, working history
- Thickness
 - Rolling mill quality
 - Design vs. manufacturing specs
- Tooling Errors



Conclusions

- Some Variations Easily Explained
 - Deterministic parameter changes
 - Thickness and Material Selection Δm_{p} (Material Parameter)
 - Intentional Input changes
 - Depth changes Δe_s (Equipment state)
- Other Variations ???
 - Property Variations within Material Δm_p
 - Machine Errors Δe_p and Δe_s (e.g. deflection and position error)

$$\Delta Y = \frac{\partial Y}{\partial \alpha} \Delta \alpha + \frac{\partial Y}{\partial u} \Delta u$$



Conclusions for Brake Bending

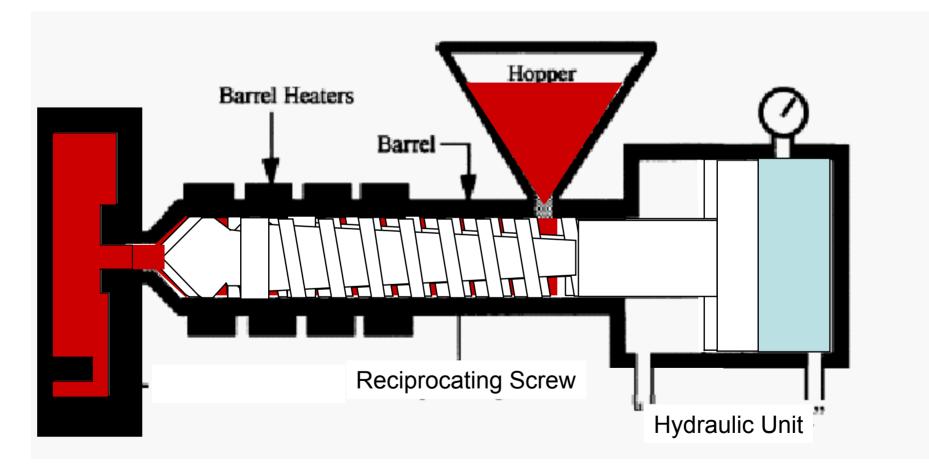
- Equipment Errors have Strong Effect on Final Shape
 - Punch Penetration
 - Die Width

-> Δe_s (Equipment state)

- -> Δe_p (Equipment Parameter)
- SO WHAT? \longrightarrow Large $\partial Y/\partial \alpha$ Large $\Delta \alpha$



Injection Molding





Injection Molding Process

Process Type?

Equipment States and Properties?

Material States and Properties?

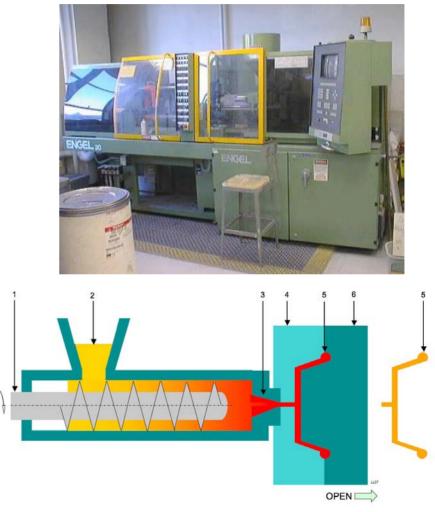


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Geometry Determinants

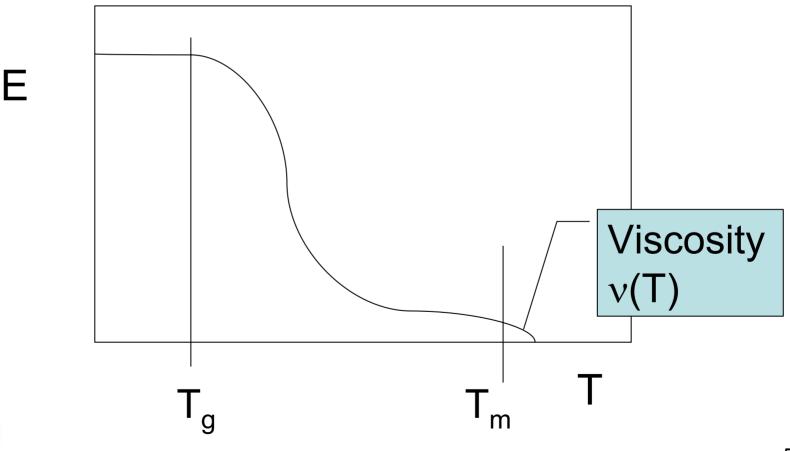
- Mold Shape
- Material Shape Change upon Cooling
 - Residual Stress Effect
 - Thermal Expansion or contraction
- Extent of Mold Filling







 $\mathsf{P} = \mathsf{R}(v) \mathsf{Q}$



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Manufacturing

Effect of Temperature on Flow

Q = P/R R = resistance to flow αv $v(T) = Ae^{ER(T_0-T)}$

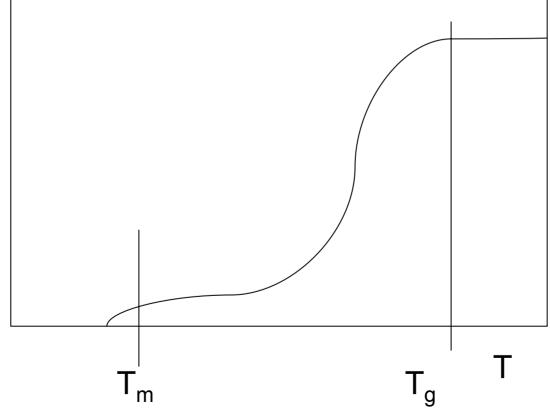
where:

- T = temperature
- R = gas constant
- E = activation energy for viscosity



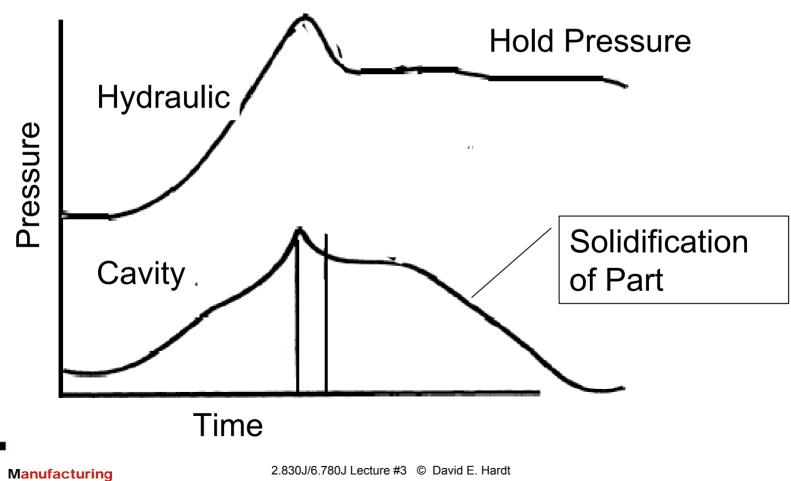
Key Material Properties: Cooling







Packing Phase



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Heat Transfer: Filling

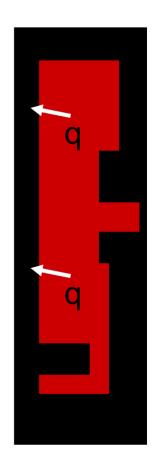
- $T_{part} > T_{mold}$ therefore always cooling
- Interior hotter than surface
- If T_{part} on surface < T_g flow stops

 Short Shot
- Viscosity is strong function of Temperature



Heat Transfer in the Mold

- $q = k A \partial T / \partial x$
 - Rate decreases as $\partial T/\partial x$ decreases
 - Mold heat & polymer cools
- $dT/dt = \alpha \partial T^2/\partial x^2$
 - $-\alpha = k / \rho C_p$
 - Polymers have low k and high Cp





Process Control Issues

- Control Change in Shape upon Cooling
 - Consistent Mold Filling
 - Consistent Mold Pressure
 - Consistent Residual Stresses
 - Consistent Thermal environment
 - Consistent Thermal Distortion



Typical Equipment Control Systems

- Injection Velocity or Injection Pressure
- Nozzle Temperature
- Mold Temperature
- Barrel Heater Temperature

Equipment States



Sources of Variation

- Material Properties
 - Flow Properties
 - v(T) relationship (especially if moist)
 - Thermal properties (ditto)
 - Also effects of "regrind"



Example: Effect of Blending

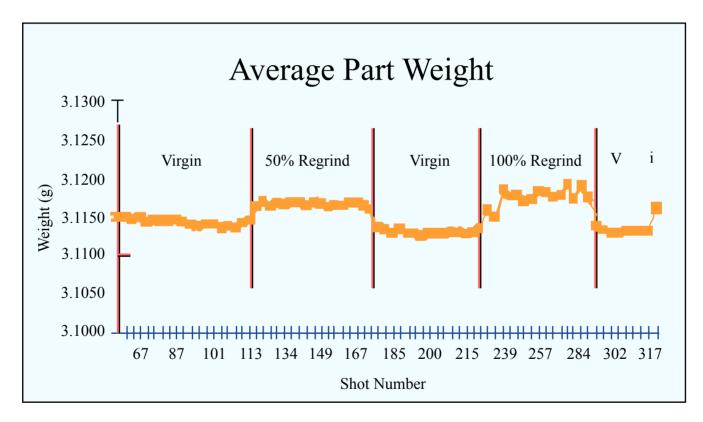


Figure by MIT OpenCourseWare.

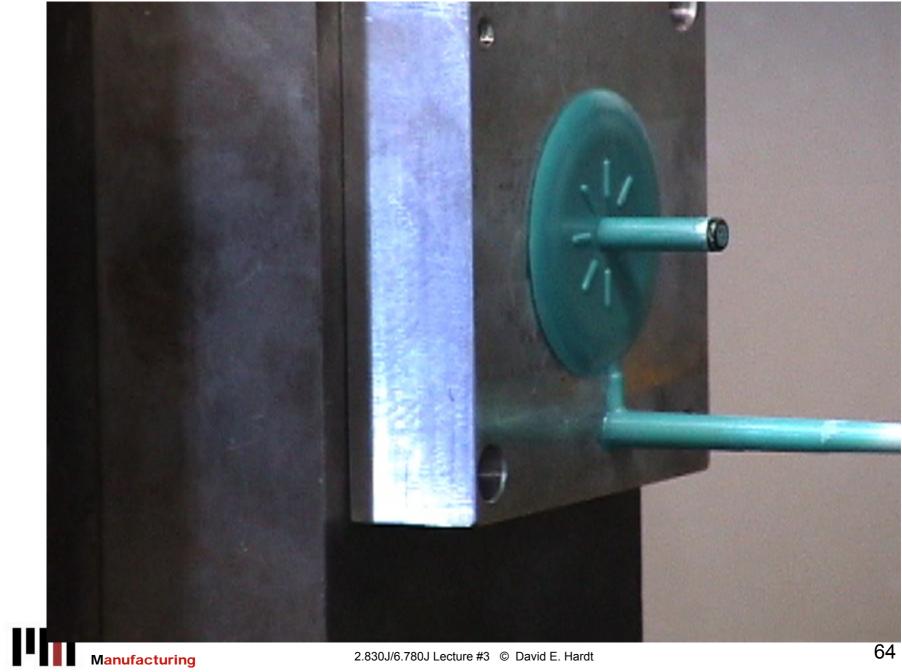


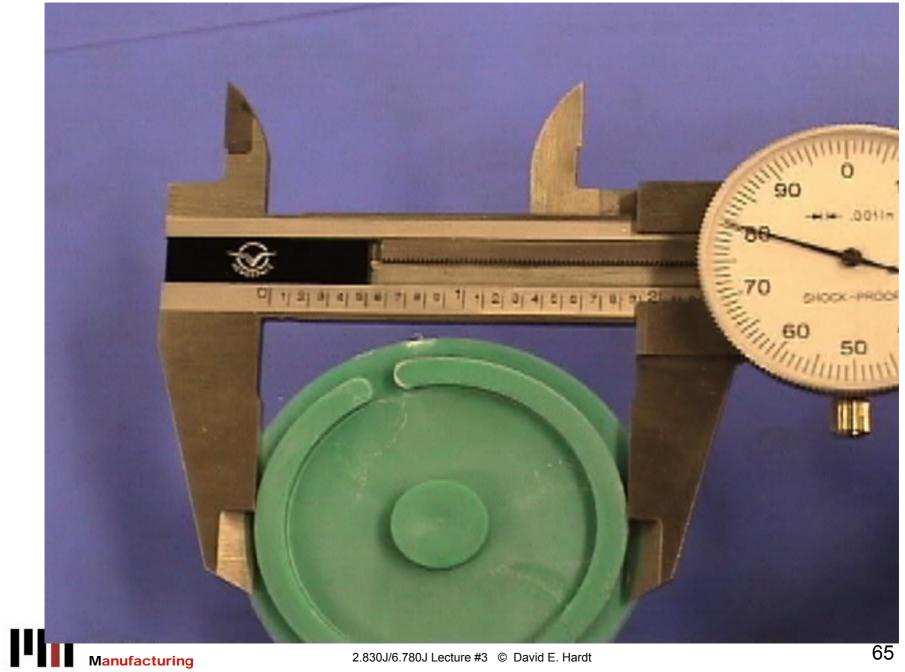
Lab Data

- Variable Hold
 Time
- Variable Injection
 Velocity

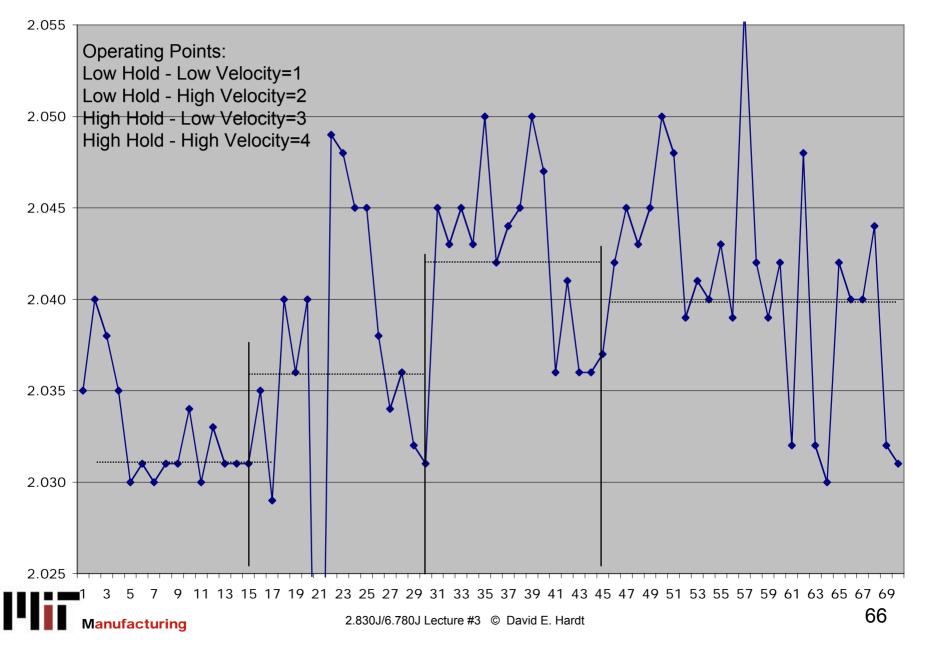




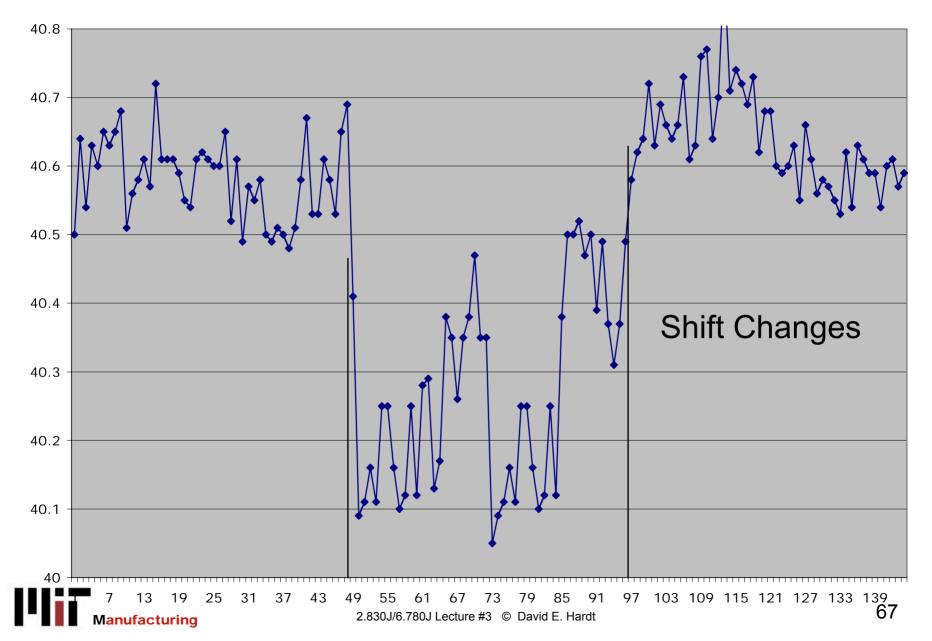




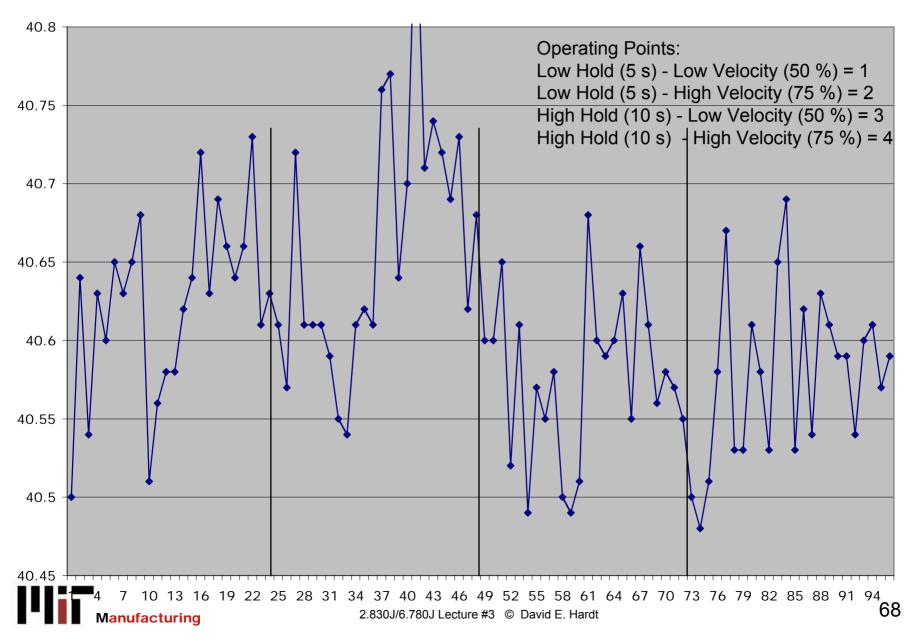
Injection Molding Data



Injection Molding NTU



I.M. NTU (no Group 1)



Sources of Variation

- Equipment Properties
 - Heat Transfer Properties
 - Mold Flow Passages
- Equipment States
 - Barrel and Nozzle Temperatures
 - Mold Temperatures
 - Flow Rates
 - Packing Pressure



Conclusions

- I.M. is a Complex, Parallel Formation Process
- Strong Dependence on Material Properties
 - Viscosity sensitivity
 - Heat Transfer Sensitivity
- Thermal State Must be Well Controlled
 - Many opportunities on the equipment
 - Material State very hard to do
 - Distributed
 - Interference with Process



Conclusions: Variation

 $+\frac{\partial Y}{\partial u}\Delta u$

Disturbances

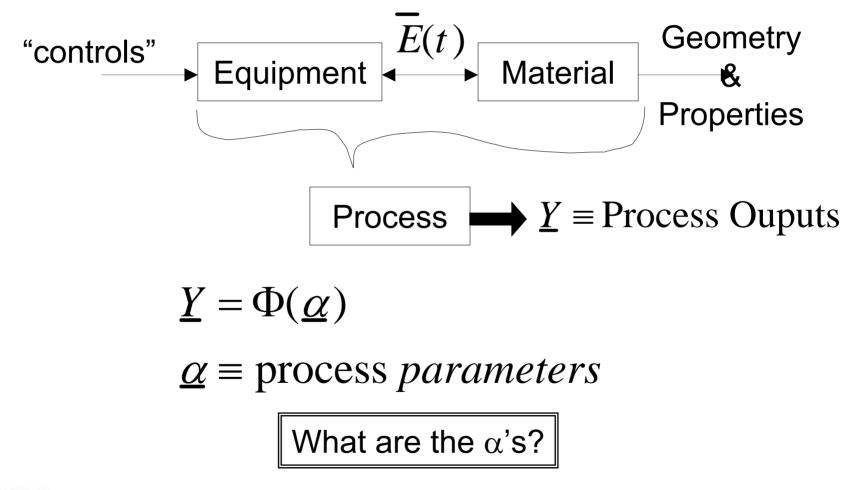
 $\Delta Y = \frac{\partial I}{\partial \alpha} \Delta \alpha$

Control Inputs: Equipment States

Equipment Property Changes Material Property Changes Material State Uncertainty Equipment State Uncertainty



Process Model for Control





What are the <u>Process Parameters</u>?

- Equipment Energy "States"
- Equipment Constitutive "Properties"
- Material Energy "States"
- Material Constitutive "Properties"



Energy States

Energy DomainEnergy or Power VariablesMechanical $F, v; P, Q \text{ or } F, d; \sigma, \varepsilon$ ElectricalV,IThermalT, ds/dt (or dq/dt)Chemicalchemical potential, rate

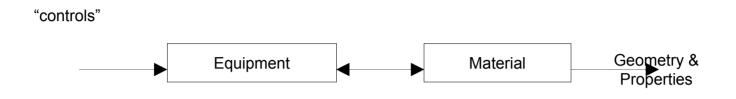


Properties

- Extensive: <u>GEOMETRY</u>
- Intensive: Constitutive Properties
 - Modulus of Elasticity, damping, mass
 - Plastic Flow Properties
 - Viscosity
 - Resistance, Inductance, Capacitance
 - Chemical Reactivity
 - Heat Transfer Coefficient
- Which has the highest precision?



A Model for Process Variations



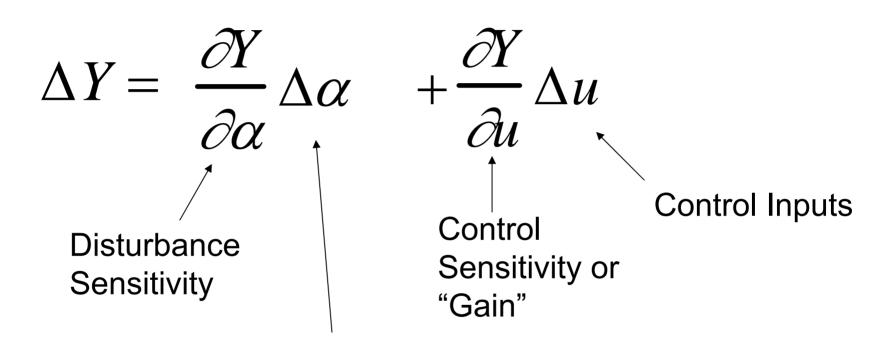
- Recall: $\underline{Y} = \Phi(\underline{\alpha})$
- One or more α 's "qualify" as inputs : <u>u</u>

$$\underline{Y} = \Phi(\underline{\alpha}, \underline{u});$$
 $\underline{u} = \text{vector of inputs}$

• The first order Variation ΔY gives the "Variation Equation"



The Variation Equation



Disturbances



Primary Process Control Goal: <u>Minimize</u> <u> ΔY </u>

How do we make $\Delta Y \rightarrow 0$?

$$\Delta Y = \frac{\partial Y}{\partial \alpha} \Delta \alpha + \frac{\partial Y}{\partial u} \Delta u$$

- hold u fixed ($\Delta \underline{u} = 0$)
 - operator training (SOP's)
 - good steady-state machine physics
- minimize disturbances

 $\Box \Delta \alpha \rightarrow \Delta \alpha_{\min}$

This is the goal of Statistical Process Control (SPC)



OR

$$\Delta Y = \frac{\partial Y}{\partial \alpha} \Delta \alpha + \frac{\partial Y}{\partial u} \Delta u \qquad \Delta Y \to 0$$

- hold u fixed $(\Delta \underline{u} = 0)$
- minimize the term: $\frac{\partial Y}{\partial \alpha}$ the disturbance sensitivity

This is the goal of Process Optimization

•Assuming
$$\frac{\partial Y}{\partial \alpha} = \Phi(\underline{\alpha})$$
 $\underline{\alpha}$ = operating point



OR

$$\Delta Y = \frac{\partial Y}{\partial \alpha} \Delta \alpha + \frac{\partial Y}{\partial u} \Delta u \qquad \Delta Y \to 0$$

• manipulate $\Delta \underline{u}$ by measuring ΔY such that

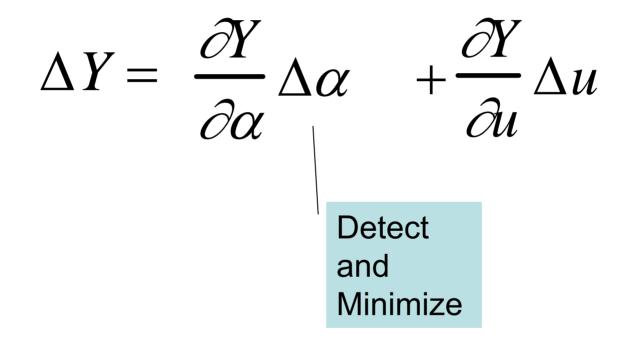
$$\Delta u \frac{\partial Y}{\partial u} = -\frac{\partial Y}{\partial \alpha} \Delta \alpha$$

This is the goal of Process Feedback Control

•Compensating for (not eliminating) disturbances

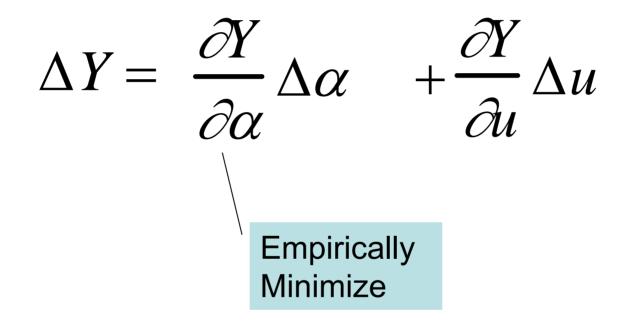


Statistical Process Control



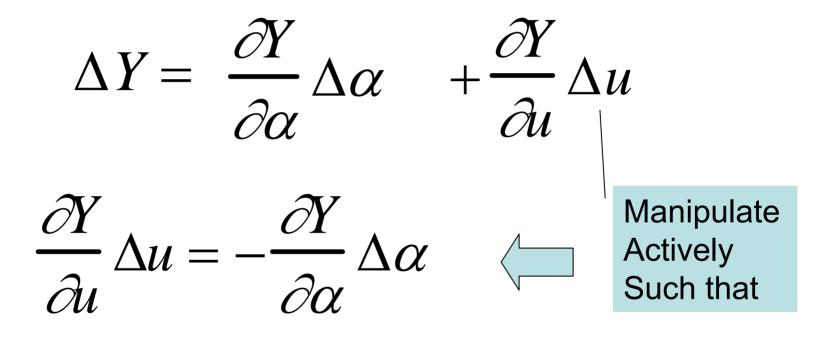


Process Optimization





Output Feedback Control



Compensate for Disturbances



Process Control Hierarchy

Reduce Disturbances

- Good Housekeeping
- Standard Operations (SOP's)
- Statistical Analysis and Identification of Sources (SPC)
- Feedback Control of Machines
- Reduce Sensitivity (increase "Robustness")
 - Measure Sensitivities via Designed Experiments
 - Adjust "free" parameters to minimize
- Measure output and manipulate inputs
 - Feedback control of Output(s)

